

# CORIAL 200

- **Precise control of ion energy** to adjust etch profile (isotropic & anisotropic),
- **Multi-step processes** to achieve selective etching of SiO<sub>2</sub> versus TiN and silicon,
- **Anisotropic etching without corrosion** to maintain electrical functionality for Cu technologies,
- **Fast etch with no damages** to display all layers in microsections,
- **Stability of equipment and process** for deprocessing of integrated circuits with many metal levels (9 levels).